at least one of the images and a measured local temperature value to calculate an AF step code, and calculate a focal length variation based on a reference AF step code. The focal length variation may be used with the binocular disparity to calculate the depth of the object. The reference AF step code may be calculated separately based on images captured by the image apparatus in association with a measured reference local temperature value. At least the reference AF step code may be stored in a memory of the image apparatus, and the image apparatus may access the stored reference AF step code to calculate the focal length variation based on the calculated AF step code associated with the current local temperature value.

[0064] FIG. 9 is a block diagram of an image sensor 100 according to some example embodiments of the inventive concepts. The image sensor 100 may include the image sensor 10. The image sensor 100 may be included in an image apparatus 1. As illustrated, the image sensor 100 may include a pixel array 110, a control unit 125, a row decoder 133, a row driver 135, a column decoder 153, a column driver 155, and a plurality of analog-digital converters (ADCs) 171, 173, and 175.

[0065] The pixel array 110 may sense incident light reflected from an object to generate object information OBI1 associated with the object and/or image information IMI associated with the object. Such information may include images captured ("generated") by one or more pixels of the pixel array 110. The pixel array 110 may include a plurality of pixels arranged in a two-dimensional matrix. The pixel array 110 may include a plurality of pixel layers 111, 113, and 115. In some example embodiments, the pixel array 110 includes three pixel layers 111, 113, and 115, although the pixel array 110, in some inventive concepts, is not limited to three pixel layers.

[0066] In some example embodiments, the first pixel array 111 may be a color pixel array. For example, the color pixel array may include Bayer-pattern pixels.

[0067] In some example embodiments, the second pixel array 113 may be a depth pixel array. For example, the depth pixel array may include a plurality of 2PD pixels or metal shield pixels. In some example embodiments, the second pixel array 113 may include at least one temperature sensor TS to perform depth correction depending on temperature.

[0068] In some example embodiments, the third pixel array 115 may be a thermal pixel array. For example, the thermal pixel array may include a plurality of temperature pixels.

[0069] The pixel array 110 may be configured to include at least two pixel arrays to perform different functions.

[0070] The control unit 125 may generate control signal(s) to control operations of the row decoder 133, the row decoder 135, the column decoder 153, the column driver 155, and the analog-digital converts (ADCs) 171, 173, and 175. For example, the control unit 125 may generate a plurality of row control signals to select a specific one of the row lines that are included in the stacked pixel layers 111, 113, and 115, respectively.

[0071] The row decoder 113 may decode a plurality of row control signals, e.g., row address signals output from the control unit 125 and output a plurality of row selection signals according to a decoding result. In response to the row selection signals output from the row decoder 133, the row

driver 135 may drive pixels included in at least one of the rows that are included in the pixel layers 111, 113, and 115, respectively.

[0072] The column decoder 153 may decode a plurality of column control signals, e.g., column address signals output from the control unit 125 and output a plurality of column selection signals according to a decoding result. In response to the column selection signals output from the column decoder 153, the column driver 155 may drive a plurality of column lines that are included in the pixels layers 111, 113, and 115, respectively.

[0073] For brevity of description, it is shown that the image sensor 100 includes one row driver 135 and one column driver 155. However, in some example embodiments, the image sensor 100 may include a plurality of row driver or column drivers to drive a plurality of row lines or column lines. The image sensor 100 may include a plurality of row decoders or column decoders.

[0074] Each of the analog-digital converters (ADCs) 171, 173, and 175 may analog-to-digitally convert signals output from the pixel arrays 111, 113, and 115 and output the analog-to-digitally converted signals to an image signal processor (ISP) 200 as image data. For example, image data may include object information OBI1 and/or image information IMI.

[0075] In some example embodiments, each of the analog-digital converters (ADCs) 171, 173, and 175 may further include a correlated double sampling (CDS) circuit to perform correlated double sampling on signals that are output from the pixel layers 11, 113, and 115, respectively. Each of the analog-digital converters (ADCs) 171, 173, and 175 may compare a correlated-double-sampled signal with a lamp signal and output a comparison result as image data.

[0076] The image signal processor (ISP) 200 disposed outside the image sensor 100 processes and displays the image data. As described in FIGS. 1 to 8, the image sensor 100 may be configured to correct depth according to local temperature values measured by a temperature sensor TS.

[0077] Example embodiments of inventive concepts may be applied to a data processing system.

[0078] FIG. 10 is a block diagram of a handheld terminal 1000 according to some example embodiments of the inventive concepts. As illustrated, the handheld terminal 1000 includes an image apparatus 1100, a wireless transceiving unit 1200, an audio processing unit 1300, an image file generation unit 1400, a nonvolatile memory device 1500, a user interface 1600, and a controller 1700.

[0079] The image apparatus 110 may include the image apparatus 1. The image apparatus 1100 includes a lens 1110, an image sensor 1120, an image single processor 1130, and a display unit 1140. In some example embodiments, the image sensor 1120 may include a pixel array to measure depth described in FIGS. 1 to 8. The image apparatus 1100 may include at least one temperature sensor TS that is disposed at a portion of the lens 1110, outside the lens 1110 or inside the image sensor 1120 and measures temperature.

**[0080]** The image signal processor **1130** may include a temperature focal length variation table F(T). The image apparatus **1100** may use the temperature focal length variation table F(T) to correct a determined depth of an object relative to the image apparatus **1** depending on temperature of the lens **1110** and ambient temperature around the lens **1110**, as described with reference to FIGS. **1** to **8**. In FIG. **10**, the temperature focal length variation table F(T) is stored in